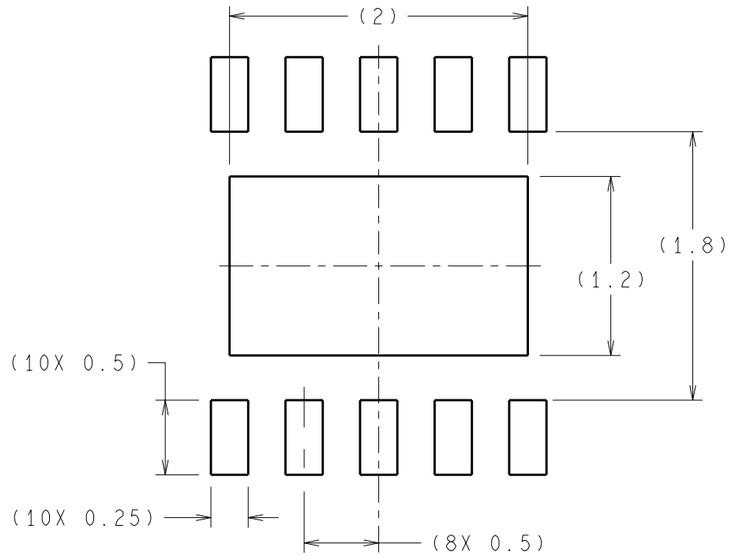
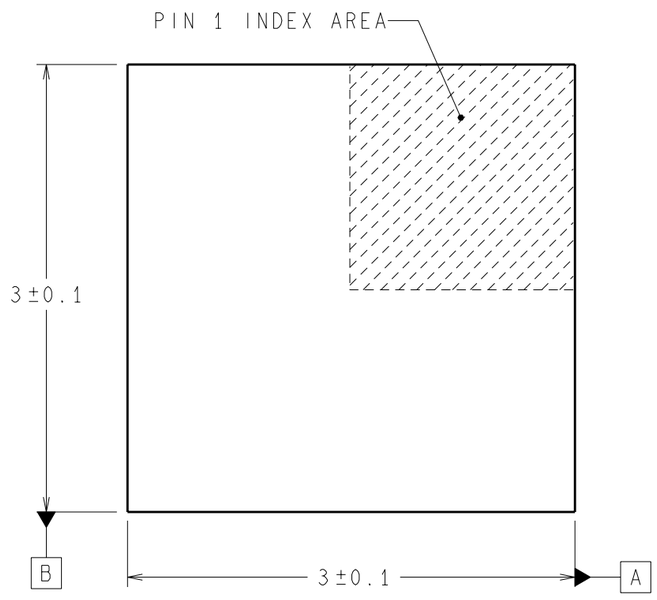
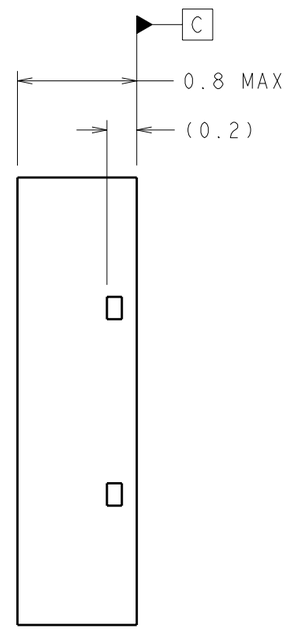
| REVISIONS | | | | |
|---|---|---|---|---|
| REV | DESCRIPTION | E.C.N. | DATE | BY/APP'D |
| A | RELEASE TO DOCUMENT CONTROL | 12478 | 07/17/2000 | SN/TL/AL |
| B | ADD PIN 1 ID DIM'S; UPDATE NOTE 2; CHANGE DWG FORMAT TO B SIZE | 909 | 01/23/2003 | TL/JB |

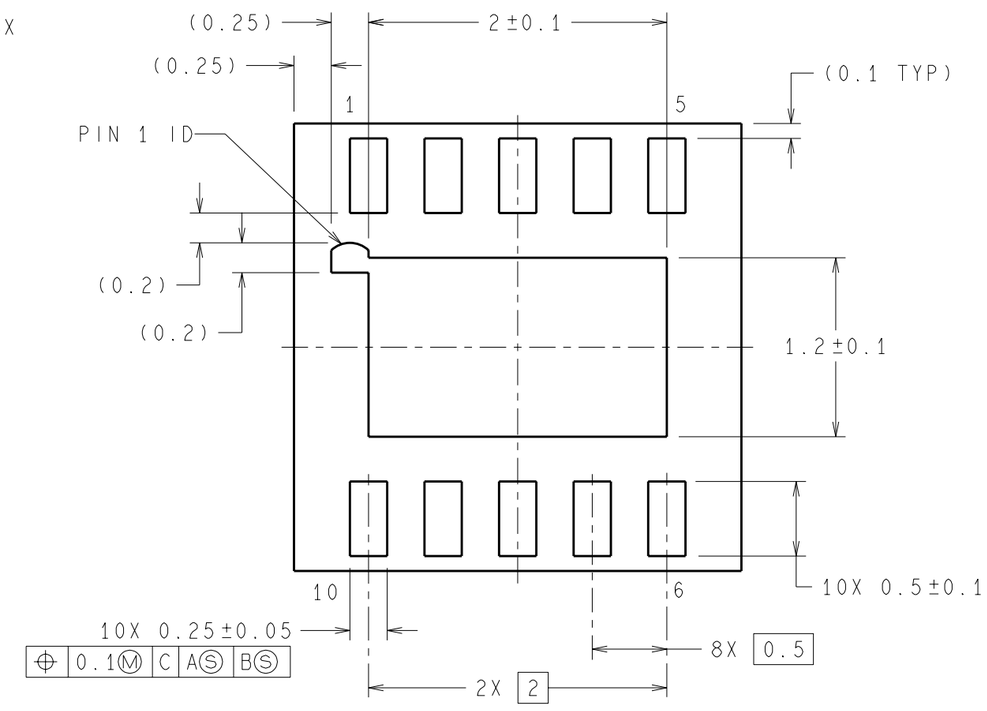



**RECOMMENDED LAND PATTERN**
1:1 RATION WITH PKG SOLDER PADS

**DIMENSIONS ARE IN MILLIMETERS**




NOTES : UNLESS OTHERWISE SPECIFIED.

1. STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM LEAD/TIN (SOLDER) ON COPPER.

2. NO JEDEC REGISTRATION AS OF JANUARY 2003.

| APPROVALS | DATE |
|---|---|
| DRAWN N.SANTHIRAN | 07/17/2000 |
| DFTG. CHK. MARTA SUCHY | 01/23/2003 |
| ENGR. CHK. JAIME BAYAN | 01/23/2003 |

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, DUAL, 3 X 3 X 0.75 mm BODY, 10 LD, 0.5 mm PITCH

| SCALE | SIZE | DRAWING NUMBER | REV |
|---|---|---|---|
| NTS | B | (SC)MKT-LDA10A | B |

FORMERLY: N/A SHEET 1 of 1